Flex Reference Designs Optimized for Hyperscale Data Centers

At Flex, we understand the complexities of hyperscale infrastructure. The solutions we deliver are optimized for performance, power and cost for cloud-scale deployments. We use technology building blocks, based on your unique requirements and time-to-market goals, to deliver customized solutions — from compute and storage nodes to fully integrated racks.

Our combination of strong design and engineering services with broad manufacturing reach is what sets us apart. We´ll customize our reference designs to provide server and storage platforms that enable both the latest technology and optimal manufacturability —whatever the scale—all while delivering the highest levels of value and performance.

Bodega Bay is a next generation reference platform that demonstrates capabilities to support cloud-scale deployments based on the OCP ORV3 infrastructure. Flex actively contributes to and supports Open Compute Project open hardware standards and the new ORV3 specification. With your partnership, Bodega Bay can be customized to your specific needs.

Specifications

Form Factor	• 1OU ORV3, rack-mount with front I/O • Rack-level power via 48V busbar • 537mm (W) x 44.5mm (H) x 805mm (D)
Compute	• Supports two next-generation Intel® Xeon® Scalable processors targeted for Q2 2022 • Supports up to 300W TDP
Memory	• 32x DDR5 DIMMs sockets • RDIMM/LRDIMM up to 4400 MT/s (2DPC)
Storage	• 8x E1.S 15mm NVMe SSDs (front) • 2x internal M.2 modules (22110) • 2x internal SATA-DOM
Networking	• Ethernet, Main, NC-SI support, 2 x SFP56, 50GbE • Ethernet, Management, 1 x RJ45, 1GbE • De-population options for Front I/O configuration
Integrated I/O	• 2x USB 3.0 ports (Front) • 2x USB 3.0 ports – Rear • 1x serial port (Rear) • 1x VGA port (Rear)
Front I/O Expansion	• 2x Full-Height, Half-Length PCIe x16 slots • 2x OCP 3.0 mezzanine slots
Management	• AST2600 BMC with IPMI and IKVM support • Supports 1x 1GbE RJ45 management port
Security	• Trusted Platform Module (TPM) 2.0 support: module or integrated • BIOS/BMC security: Intel® Platform Firmware Resilience (Intel® PFR)

Flex (Reg. No. 199002645H) is the manufacturing partner of choice that helps a diverse customer base design and build products that improve the world. Through the collective strength of a global workforce across 30 countries and responsible, sustainable operations, Flex delivers technology innovation, supply chain, and manufacturing solutions to various industries and end markets.

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